



Material Content Data Sheet



Sales Product Name	SPD08P06P G	Issued	28. April 2021
MA#	MA000451056		
Package	PG-TO252-3-311	Weight*	313.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.145	0.37	0.37	3656	3656
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		458	
	non noble metal	copper	7440-50-8	143.098	45.69	45.75	457070	457665
wire	non noble metal	aluminium	7429-90-5	0.625	0.20	0.20	1996	1996
encapsulation	inorganic material	antimonytrioxide	1309-64-4	2.012	0.64		6426	
	plastics	brominated resin	-	2.155	0.69		6885	
	organic material	carbon black	1333-86-4	2.299	0.73		7344	
	plastics	epoxy resin	-	19.399	6.20		61962	
	inorganic material	silicondioxide	60676-86-0	117.830	37.64	45.90	376361	458978
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11946	11946
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.026	0.01		83	
	noble metal	silver	7440-22-4	0.032	0.01		104	
	non noble metal	lead	7439-92-1	1.240	0.40	0.42	3961	4148
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61255	61334
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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